

Title (en)  
PROCESS AND APPARATUS FOR PARTICLE IMPLANTATION IN SOLIDS

Publication  
**EP 0112238 A3 19840725 (FR)**

Application  
**EP 83402341 A 19831205**

Priority  
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Abstract (en)  
[origin: US4585945A] In a process for implanting particles in a solid in which is produced a substantially parallel beam of high-energy primary particles secondary particles are placed in the path of the latter and by interaction with the primary particles are projected towards the target with a sufficiently high energy level to penetrate the same. The secondary particles are in the gaseous state, the gas occupying an area facing the target. The apparatus for implanting particles in a solid has a target support and a solid target in a vacuum enclosure. It also has a source of high-energy primary particles, which supplies a substantially parallel beam thereof, a source of the secondary particles to be implanted in the target, a means for confining the secondary particles and communicating with the secondary particle source and having a primary opening for receiving the primary particle beam and a secondary opening for ejecting the secondary recoil particles towards the target.

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Citation (search report)  
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• [A] US 4108751 A 19780822 - KING WILLIAM J  
• [A] NUCLEAR INSTRUMENTS AND METHODS, volume 182/183, partie 1, avril-mai 1981 (AMSTERDAM, NL) T. WADA "A new recoil implantation in Si using electron bombardment", pages 131-136

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